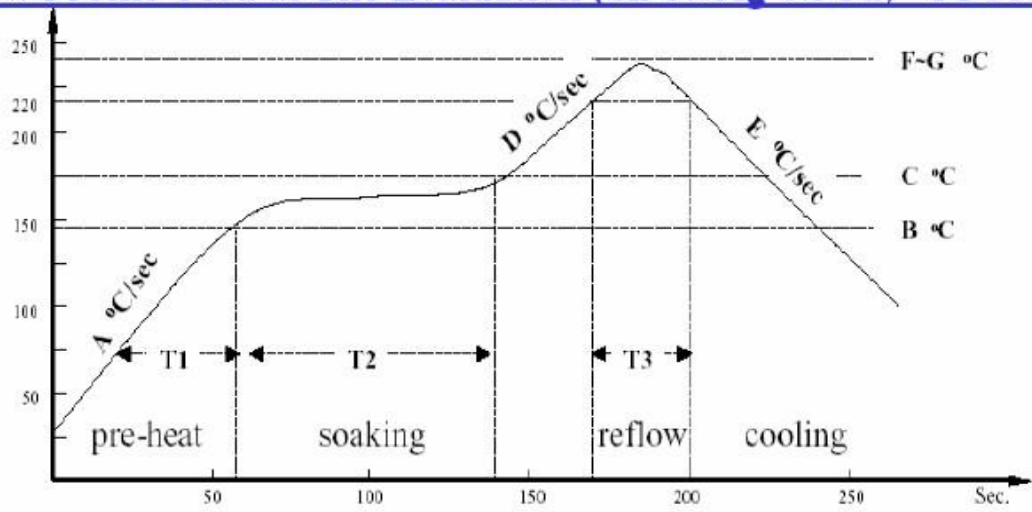


### Reflow Profile Used at The Evaluation (Sn-3.0Ag-0.5Cu) –PF606-P



A: ramp up rate during preheat:	1.5-3.0 °C/sec
B-C: soaking temperature:	170± 15 °C
D: ramp up rate during reflow:	1.2-2.3 °C/sec
E: ramp down rate during cooling:	1.7-2.2 °C/sec
F-G: peak temperature:	240± 10 °C
T1: preheat time:	65± 15 sec
T2: dwel time during soaking:	75± 15 sec
T3: time above 220 °C :	30± 10 sec